PRODUCT CHANGE NOTICE

Alternate Bond Wire Material for Assembly of the Listed Intersil DFN/QFN Packaged Products

Refer to:
PCN11117

Date: November 21, 2011

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To: Our Valued Intersil Customer

Subject: **Alternate Bond Wire Material for Assembly of the Listed Intersil DFN/QFN Packaged Products** – *STATS ChipPAC Malaysia*

This notice is to inform you that Intersil has qualified copper bond wire as an alternate to the gold bond wire currently used for assembly of the listed DFN/QFN (Quad Flat No Lead / Dual Flat No Lead) packaged products at the STATS ChipPAC (SCM) facility, located in Kuala Lumpur, Malaysia. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep and equivalent reliability performance. As of this notice, all product and package specific qualification activities are complete.

Products affected:

ISL85402IRZ	ISL97670IRZR5497	ISL98602IRAAZ-T	ISL9491ERZ-TR5370
ISL85402IRZ-T	ISL97680IRZ	ISL98602IRAAZ-T7A	ISL98603IRAAZ
ISL85402IRZ-T7A	ISL97680IRZ-T	ISL98602IRAAZ-TK	ISL98603IRAAZ-T
ISL85402IRZ-TK	ISL97680IRZ-TK	ISL9110IRTAZ	ISL98603IRAAZ-T7A
ISL97670IRZ	ISL97684IRTZ	ISL9110IRTAZ-T	ISL98603IRAAZ-TK
ISL97670IRZ-T	ISL97684IRTZ-T	ISL9110IRTAZ-T7A	ISL6265CHRTZ
ISL97670IRZ-TK	ISL97684IRTZ-TK	ISL9491ERZ	ISL6265CHRTZ-T
ISL97670IRZ-TR5497	ISL98602IRAAZ	ISL9491ERZ-T	

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly of DFN/QFN packaged products with both copper and gold bond wire material. There will be no change in the mold compound, die attach, or package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020). The qualified material set combinations for assembly and other key items are as follows:

Key Items	SCM Current	SCM New (Alternate)
Mold Compound	Sumitomo EME-G770	Sumitomo EME-G770
Die Attach	Ablebond 8290	Ablebond 8290
Bond Wire	1.0, 1.2, or 1.3 mil Gold (Au)	1.2 mil Copper (Cu)
Moisture Sensitivity Level	1, 2, 3	3
Device Marking - Site Code	H	M

The qualification plan for copper bond wire assembly was designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Products affected by this change that are assembled using either gold or copper bond wire material are identifiable via Intersil's internal traceability system and by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at SCM with copper bond wire is "M". The site code for product assembled at SCM with gold bond wire is "H".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled using either gold or copper bond wire beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster
Intersil Corporation

PCN11117

CC: J. Touvell D. Decrosta D. Foster S. Nadarajah B. Lee N. Nichani

PCN11117 –SCM Reliability Qualification Summary

Device: ISL97645 (24L 4X4 QFN)					
Stress / Conditions	Duration	Test lots			Result
		Lot #1	Lot #2	Lot #3	
MSL classification	L3 PBFree	0/22	NA	NA	PASS
uHAST 130C / 85% RH	96 Hrs	0/84	NA	NA	PASS
Temp Cycle -65C to +150C	500 cycles	0/82	NA	NA	PASS
Wire pull after 500 TC	NA	0/6	NA	NA	PASS

Device: ISL6366 (60L 7x7 QFN)					
Stress / Conditions	Duration	Test lots			Result
		Lot #1	Lot #2	Lot #3	
MSL classification	L3 PBFree	0/22	0/22	0/22	PASS
uHAST 130C / 85% RH	96 Hrs	0/28	0/28	0/28	PASS
Temp Cycle -65C to +150C	500 cycles	0/80	0/80	0/80	PASS
Wire pull after 500 TC	NA	0/2	0/2	0/2	PASS

Device: ISL6265C (60L 7x7 QFN)					
Stress / Conditions	Duration	Test lots			Result
		Lot #1	Lot #2	Lot #3	
MSL classification	L3 PBFree	0/22	0/22	NA	PASS
uHAST 130C / 85% RH	96 Hrs	0/78	0/78	NA	PASS
Temp Cycle -65C to +150C	500 cycles	0/240	0/240	NA	PASS
Wire pull after 500 TC	NA	0/3	0/3	NA	PASS

PCN11117 –SCM Reliability Qualification Summary

Device: ISL9491 (16L 4x4 QFN)					
Stress / Conditions	Duration	Test lots			Result
		Lot #1	Lot #2	Lot #3	
MSL classification	L3 PBFree	0/77	0/77	0/77	PASS
Temp Cycle -65C to +150C	500 cycles	0/77	0/77	0/77	PASS
Wire pull after 500 TC	NA	0/2	0/2	0/2	PASS

Device: ISL98604 (40L 5x5 TQFN)					
Stress / Conditions	Duration	Test lots			Result
		Lot #1	Lot #2	Lot #3	
MSL classification	L3 PBFree	0/77	0/77	0/77	PASS
uHAST 130C / 85% RH	96 Hrs	0/40	0/30	NA	PASS
Temp Cycle -65C to +150C	500 cycles	0/77	0/77	0/77	PASS
Wire pull after 500 TC	NA	0/2	0/2	0/2	PASS